

**Date:** February 2021  
**Rev:** IX  
**No. of Components:** Two  
**Mix Ratio by Weight:** 100 : 33  
**Specific Gravity:** Part A: 1.20 Part B: 0.98  
**Pot Life:** 2 Hours  
**Shelf Life- Bulk:** One year at room temperature

**Recommended Cure: 80°C / 1 Hour**

Minimum Alternative Cure(s):  
*May not achieve performance properties listed below*  
 65°C / 3 Hours  
 23°C / 24 Hours

**NOTES:**

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.
- **TOTAL MASS SHOULD NOT EXCEED 25 GRAMS**

**Product Description:** A version of EPO-TEK® 302-3M designed to meet European regulatory requirements. It is a two component epoxy used for optical, fiber optic, and semiconductor applications. The epoxy is good for adhesive joining, sealing, potting, or as a coating.

**Typical Properties:** Cure condition: Varies as required Different batches, conditions & applications yield differing results.  
 Data below is not guaranteed. To be used as a guide only, not as a specification. \* denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	Part A: Clear, slightly yellow	Part B: Clear, yellow/orange	
* Consistency:	Pourable liquid		
* Viscosity (23°C) @ 100 rpm:	300 - 900	cPs	
Thixotropic Index:	N/A		
* Glass Transition Temp:	≥ 45	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expansion (CTE):			
	Below Tg:	63	x 10 <sup>-6</sup> in/in°C
	Above Tg:	214	x 10 <sup>-6</sup> in/in°C
Shore D Hardness:	83		
Lap Shear @ 23°C:	> 2,000	psi	
Die Shear @ 23°C:	≥ 20	Kg	8,528 psi
Degradation Temp:	364	°C	
Weight Loss:			
	@ 200°C:	0.15	%
	@ 250°C:	0.44	%
	@ 300°C:	1.64	%
Suggested Operating Temperature:	< 300 °C (Intermittent)		
Storage Modulus @ 23°C:	385,000	psi	
Particle Size:	N/A		

OPTICAL PROPERTIES @ 23°C:		
Spectral Transmission:	> 98% @ 460-1620	nm
Refractive Index (uncured):	1.5442 @589	nm

**Epoxyes and Adhesives for Demanding Applications™**

**This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.**

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